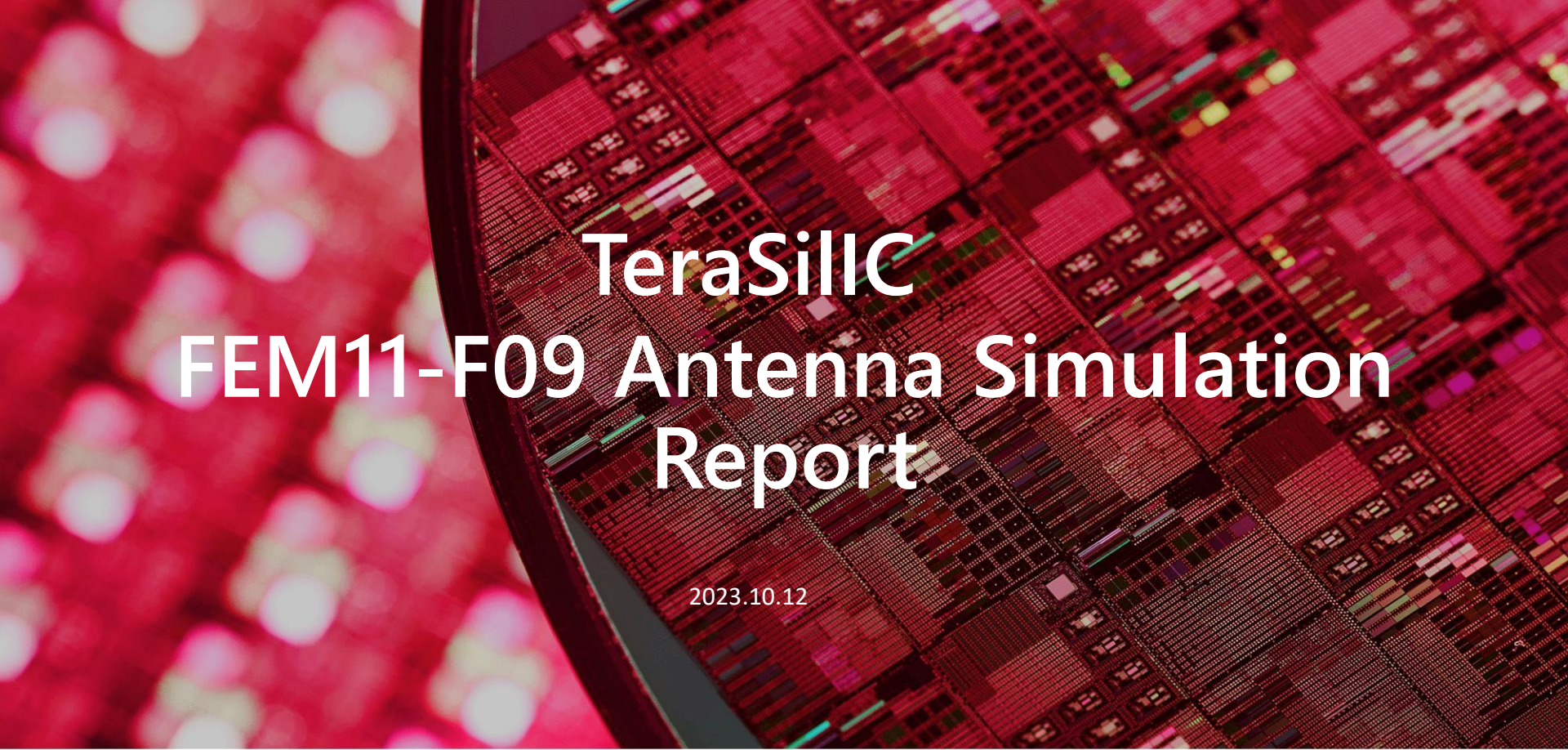


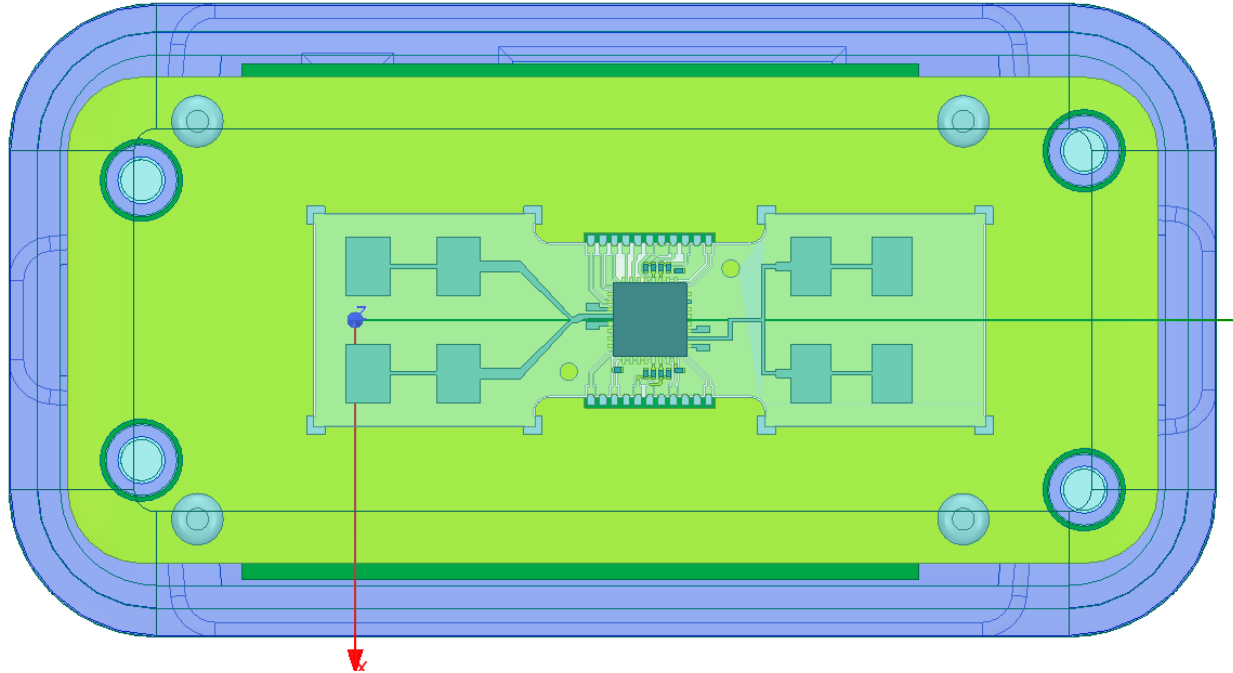
The background of the slide is a close-up, high-magnification image of a microchip. The chip's surface is covered in a dense grid of small, colorful squares (red, yellow, green, blue) representing different circuit components or solder bumps. The image is slightly out of focus, with a bokeh effect in the foreground, creating a sense of depth. The overall color palette is dominated by reds and pinks, with some cooler colors from the chip's components.

TeraSiIC FEM11-F09 Antenna Simulation Report

2023.10.12

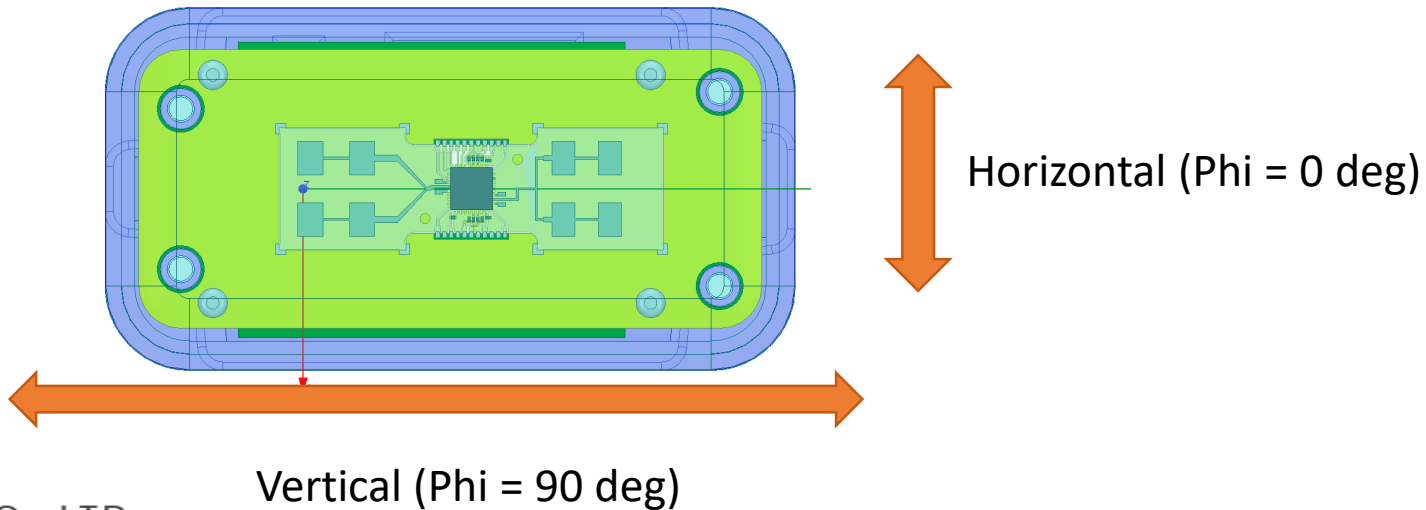
3D Model

F09



Comparison

Case	Return Loss (dB)	Isolation (dB)	Beam width (Tx) (degree)		Beam width (Rx1) (degree)	
			Horizontal	Vertical	Horizontal	Vertical
F09	<-10	<-15	77.5	110.5	78.9	104.5

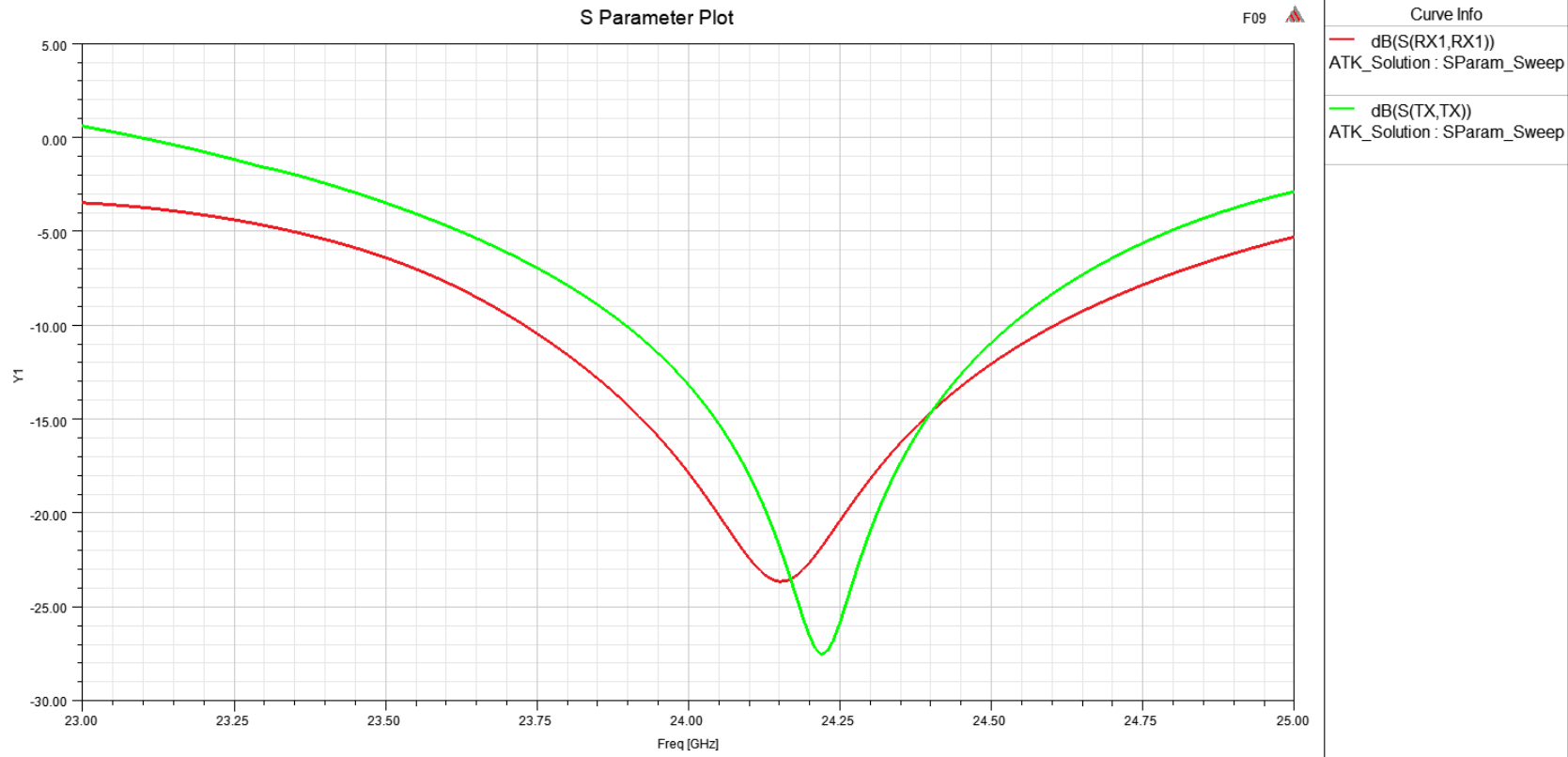


Conclusion

- 模擬結果:
 - 1) 24GHz~24.25GHz Return Loss < -10dB °
 - 2) TX-RX1 24GHz~24.25GHz Isolation < -35dB °



Return Loss



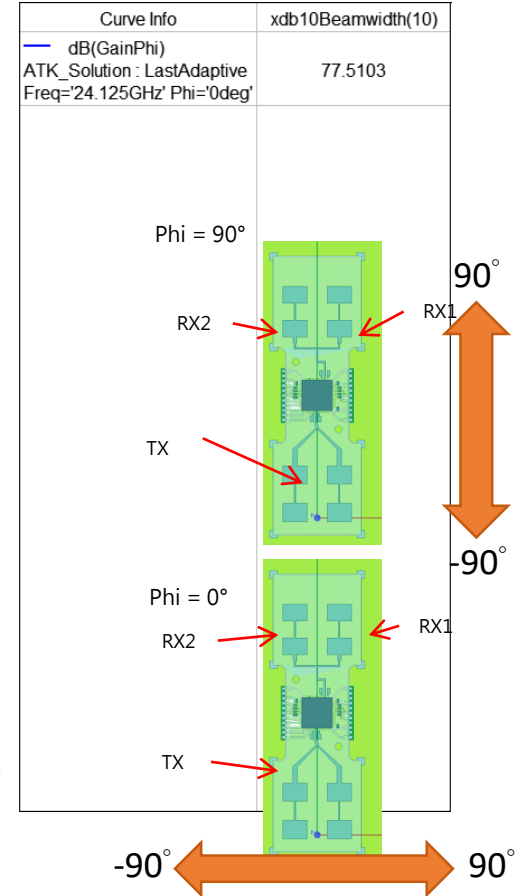
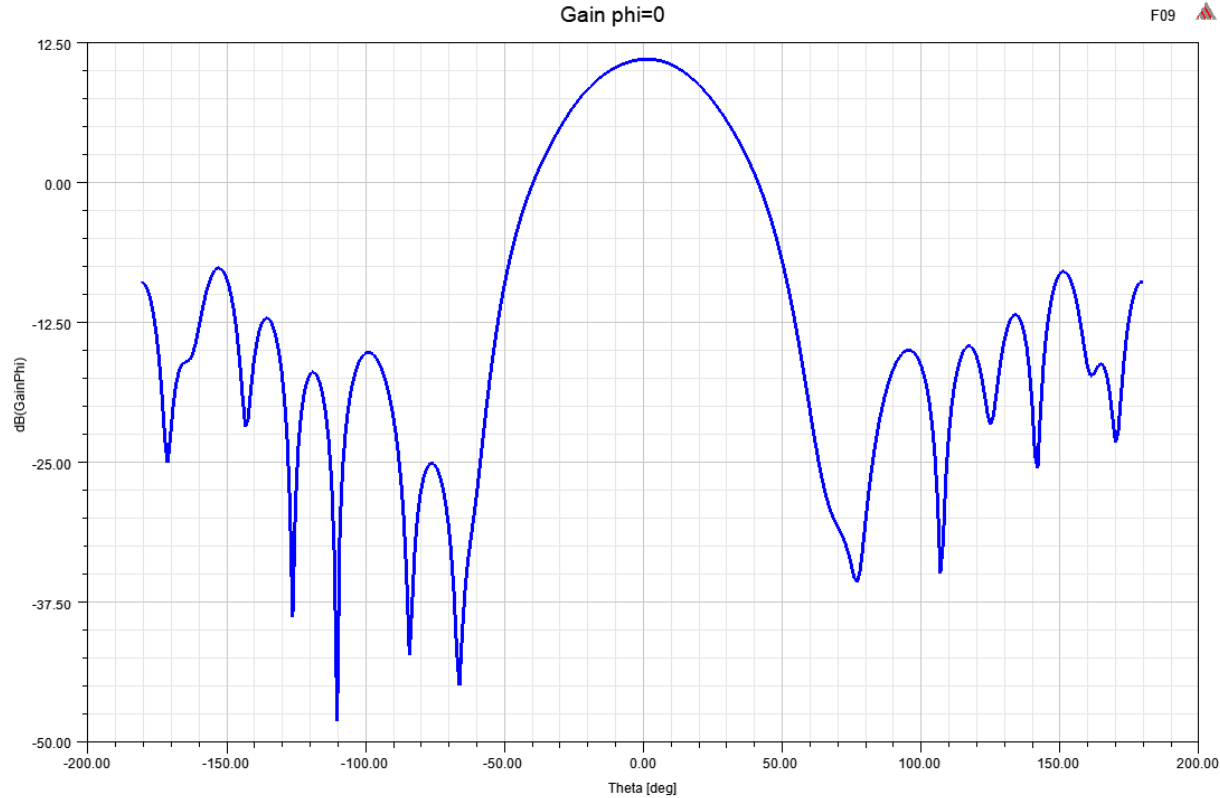
Isolation



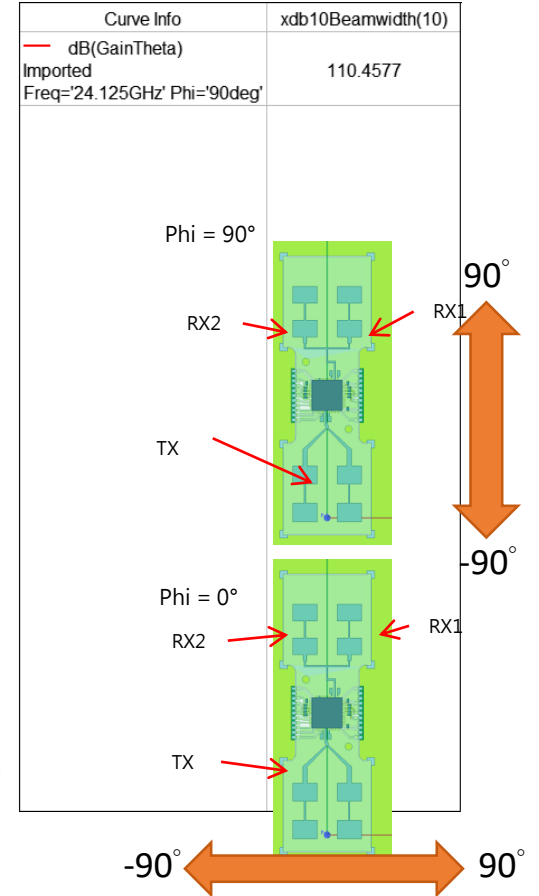
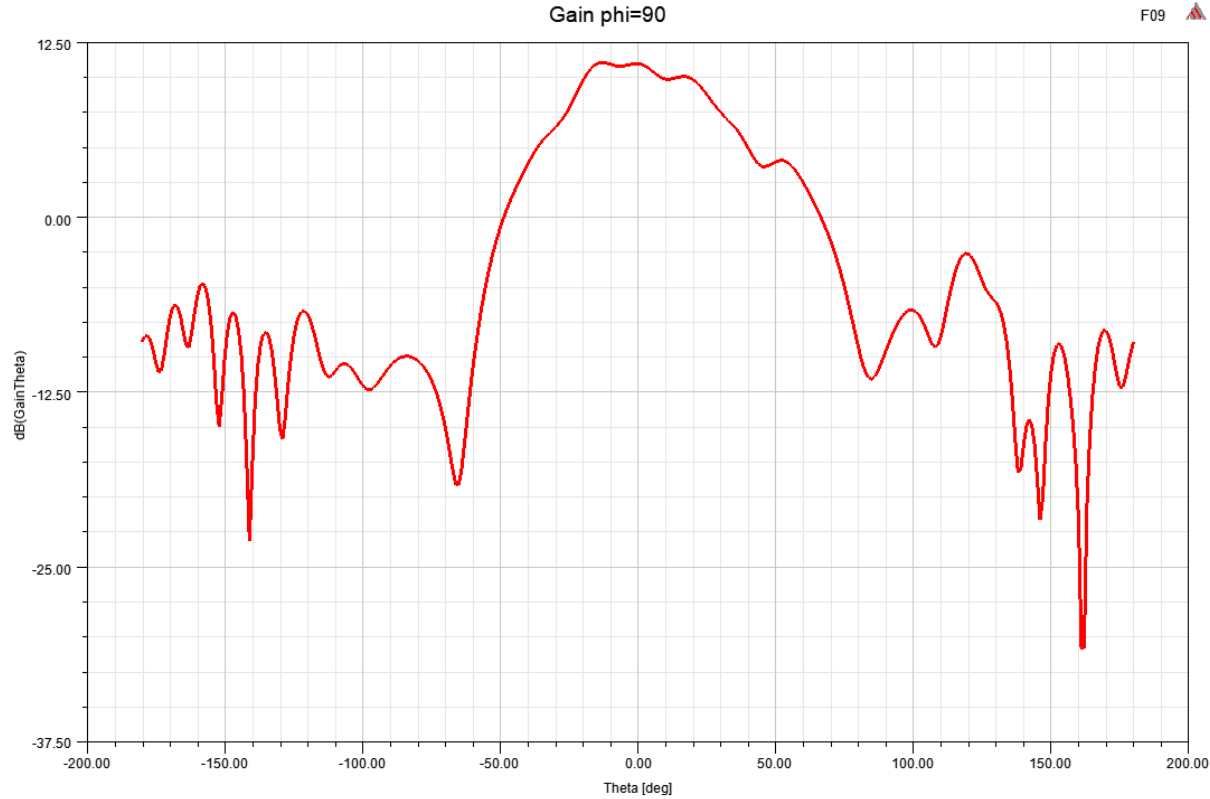
— dB(S(TX,RX1))
ATK_Solution : SParam_Sweep



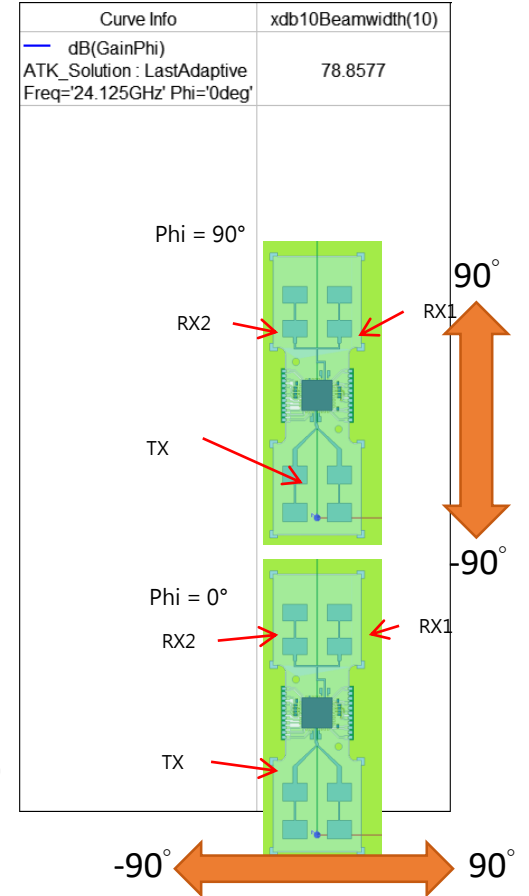
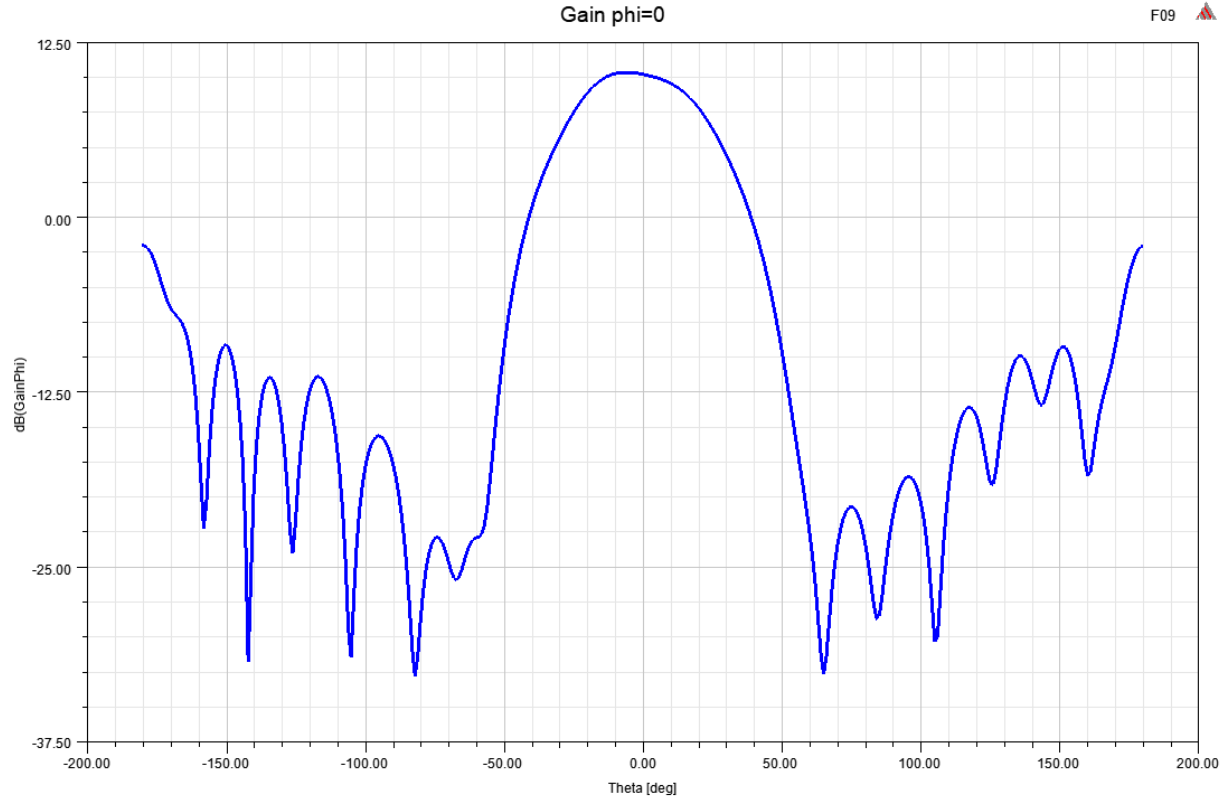
2D Pattern TX Phi=0



2D Pattern TX Phi=90



2D Pattern RX1 Phi=0



2D Pattern RX1 Phi=90

